

**XENSIV™ linear TMR position sensor**

**Features**

- Linear position sensor based on Infineon's patented VortexTMR technology
- Magnetic measurement range of  $\pm 35$  mT
- Large ratiometric output sensitivity of 5 mV/V/mT
- 5  $\mu V_{RMS}$  noise
- 0.25 mA current consumption @ 1.8 V<sub>dd</sub>
- PG-SOT23-6-4 package

**Potential applications**

- Linear position sensing
- Angle sensing
- Gaming applications

**Product validation**

Product validation according to JEDEC JESD47.

**Description**

The TLI55910 is a TMR (Tunnel Magneto Resistance) based linear position sensor. The non-amplified sensor is ideal for high accuracy and low power applications.

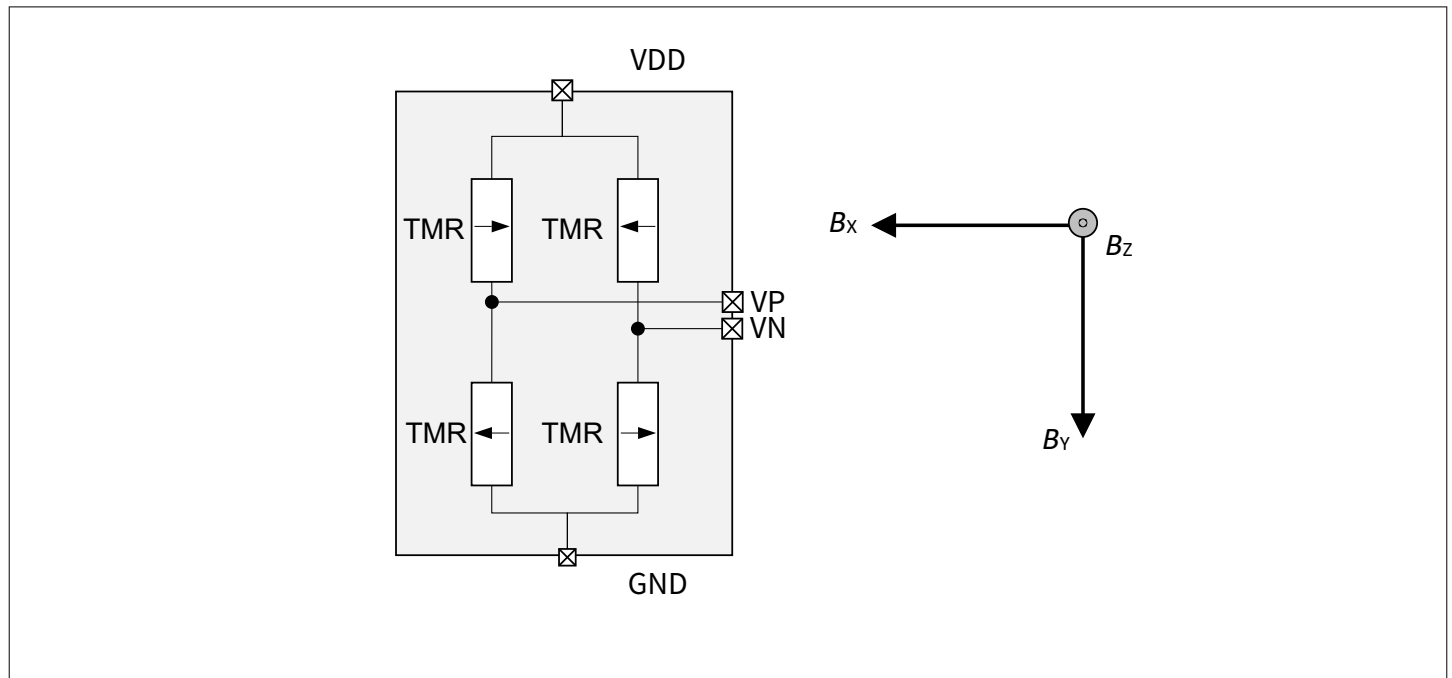


Product type	Description and feature	Package	Marking	Ordering code
TLI55910-A6E-E0001	Single TMR bridge magnetic field sensor, X sensitivity direction	PG-SOT23-6	10A	SP006118939

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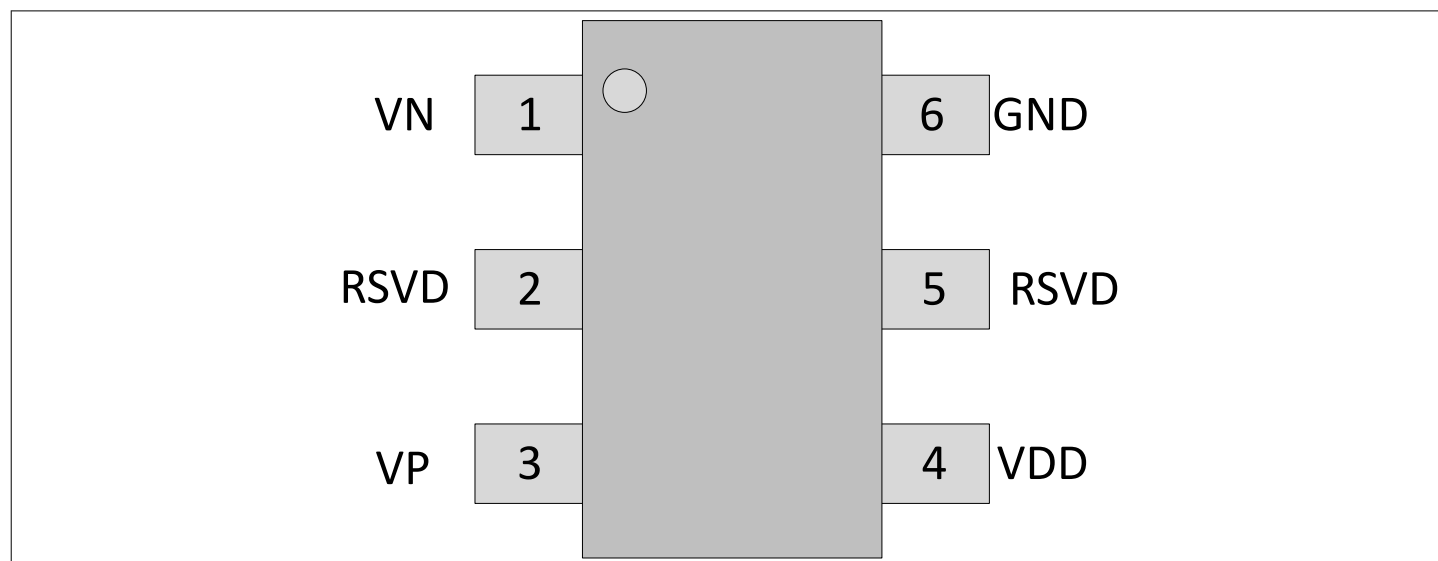
## 1 Functional block diagram



**Figure 1** Device functional block diagram

The device measures a magnetic field via a Tunnel Magneto Resistance (TMR) Wheatstone bridge. For each TMR in the block diagram an arrow is used to indicate the direction of the reference layer magnetization, which indicate the positive sensing direction of the single TMR. The output of the Wheatstone bridge is made available on the VP and VN pins.

## 2 Pin configuration



**Figure 2** Package pinout

**Table 1** Pin definitions and function

Pin No.	Symbol	Function	Comment
1	VN	Negative terminal of TMR Wheatstone bridge	–
2	RSVD	Pin shorted with sensor lead frame	Only one RSVD pin should be connected to GND
3	VP	Positive terminal of TMR Wheatstone bridge	–
4	VDD	Supply voltage	–
5	RSVD	Pin shorted with sensor lead frame	Only one RSVD pin should be connected to GND
6	GND	Ground	–

### 3 General product characteristics

#### 3.1 Absolute maximum ratings

Table 2 Absolute maximum ratings

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Electrical						
Supply voltage	V <sub>DD_ABS</sub>	-0.3	–	6.5	V	Maximum 10 hours between 5.5 V to 6.5 V
Voltage on VP and VN pins	V <sub>VPVN_ABS</sub>	0.5	–	4.5	V	
ESD voltage	V <sub>ESD_HBM</sub>	-2	–	2	kV	Human Body Model, according to ANSI/ESDA/JEDEC JS-001
ESD voltage	V <sub>ESD_CDM</sub>	-1	–	1	kV	Charged Device Model, according to ANSI/ESDA/JEDEC JS-002
Temperature						
Storage temperature	T <sub>s</sub>	-40	–	150	°C	
Junction Temperature	T <sub>J</sub>	-40	–	150	°C	
Magnetic						
Magnetic field at TMR sensing element	B <sub>TMR_ABS</sub>	-75	–	75	mT	B <sub>TMR_ABS</sub> = ±√(B <sub>X</sub> <sup>2</sup> + B <sub>Y</sub> <sup>2</sup> )

**Attention:** Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the section “functional range” is not implied. Furthermore, only single error cases are assumed. More than one stress/error case may also damage the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. During absolute maximum rating overload conditions the voltage on VDD pins with respect to ground shall not exceed the values defined by the absolute maximum ratings. Lifetime statements are an anticipation based on an extrapolation of Infineon’s qualification test results. The actual lifetime of a component depends on its form of application and type of use etc. and may deviate from such statement. Lifetime statements shall in no event extend the agreed warranty period.

#### 3.2 Functional range

The following functional range shall not be exceeded in order to ensure correct operation of the device. All parameters specified in the following sections refer to these operating conditions unless otherwise indicated.

Table 3 Functional range

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Electrical						
Operating supply voltage	V <sub>DD</sub>	1	–	5.5	V	

(table continues...)

**Table 3** (continued) **Functional range**

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Temperature						
Operating ambient temperature	$T_A$	-40	–	125	°C	
Operating junction temperature	$T_{J\_OP}$	-40	–	128	°C	
Magnetic						
Operating magnetic field at TMR sensing element	$B_{TMR}$	-35	–	35	mT	$B_{TMR} = \pm\sqrt{(B_X^2+B_Y^2)}$
Circuit						
Capacitance on VDD pin	$C_{VDD}$	–	100	–	nF	External capacitance connected to VDD pin. Typical value is a condition valid for all performance parameters unless otherwise specified
Capacitance on VP pin	$C_{VP}$	–	33	–	pF	External capacitance connected to VP pin. Typical value is a condition valid for all performance parameters unless otherwise specified
Capacitance on VN pin	$C_{VN}$	–	33	–	pF	External capacitance connected to VN pin. Typical value is a condition valid for all performance parameters unless otherwise specified

### 3.3 Thermal resistance

**Table 4** **Thermal resistance**

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Thermal resistance	$R_{th,JA}$	–	250	300	K/W	Junction to air, according to JEDEC JESD51-7

## 4 Product features

### 4.1 Electrical characteristics

**Table 5** Electrical characteristics

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Current consumption	$I_{DD}$	–	0.7	1.5	mA	$V_{DD} = 5V$
Bridge Resistance	$R_0$	5000	8200	10600	$\Omega$	$B_X = 0$
Linear temperature resistance coefficient	$T_{C\_R0}$	-950	-750	-550	ppm/K	

### 4.2 Sensing characteristics

**Table 6** Sensing characteristics

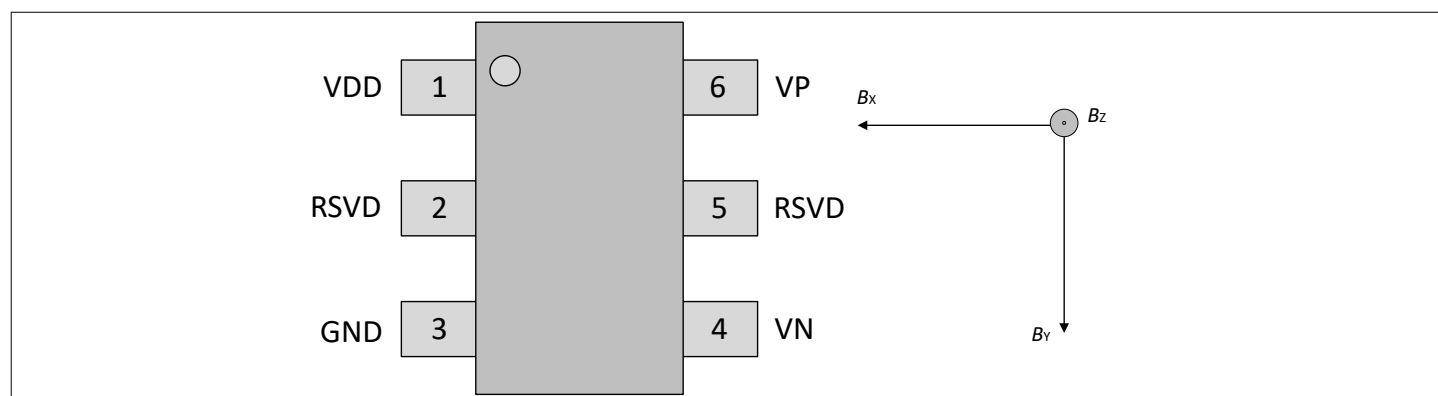
Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Sensitivity	$S$	4	4.8	6.3	mV/V/ mT	Sensitivity dependent on voltage at $V_{DD}$ pin, hence Sensitivity scales with supply voltage. $T_A = 25^\circ C$ , 0h; it can be compensated in the application by EOL-calibration at RT in the microcontroller <sup>1)</sup>
Output noise	$V_{NOISE}$	–	5	35	$\mu V_{RMS}$	BW = 1 MHz. Referenced to magnetic input field. Typical value is at RT and BW = 100 kHz
Initial offset	$E_{OFF\_INIT}$	-10	–	10	mV/V	$T_A = 25^\circ C$ , 0h; it can be compensated in the application by EOL-calibration at RT in the microcontroller <sup>1)</sup>
Linear temperature coefficient of electrical offset	$T_{CO}$	-4	–	4	$\mu V/V/K$	Difference with respect to $25^\circ C$ <sup>1)</sup>
Linear temperature coefficient of mean sensitivity	$T_{CS}$	-950	-700	-450	ppm/K	Difference with respect to $25^\circ C$ <sup>1)</sup>
Non-linearity error over temperature range 12mT	$E_{NL\ 12mT}$	-1	–	1	%	% of utilized 12mT range <sup>1)</sup>
Non-linearity error over temperature	$E_{NL\ 35mT}$	-1.8	–	1.8	%	% of utilized FS range <sup>1)</sup>
Hysteresis error over temperature	$E_{HYST}$	-0.5	–	0.5	%	% of $B_{FS}$ <sup>1)</sup>

1) Typical values are  $\pm 3\sigma$  min/max values

## 4.3 Functional description

### 4.3.1 Output voltage and current polarity

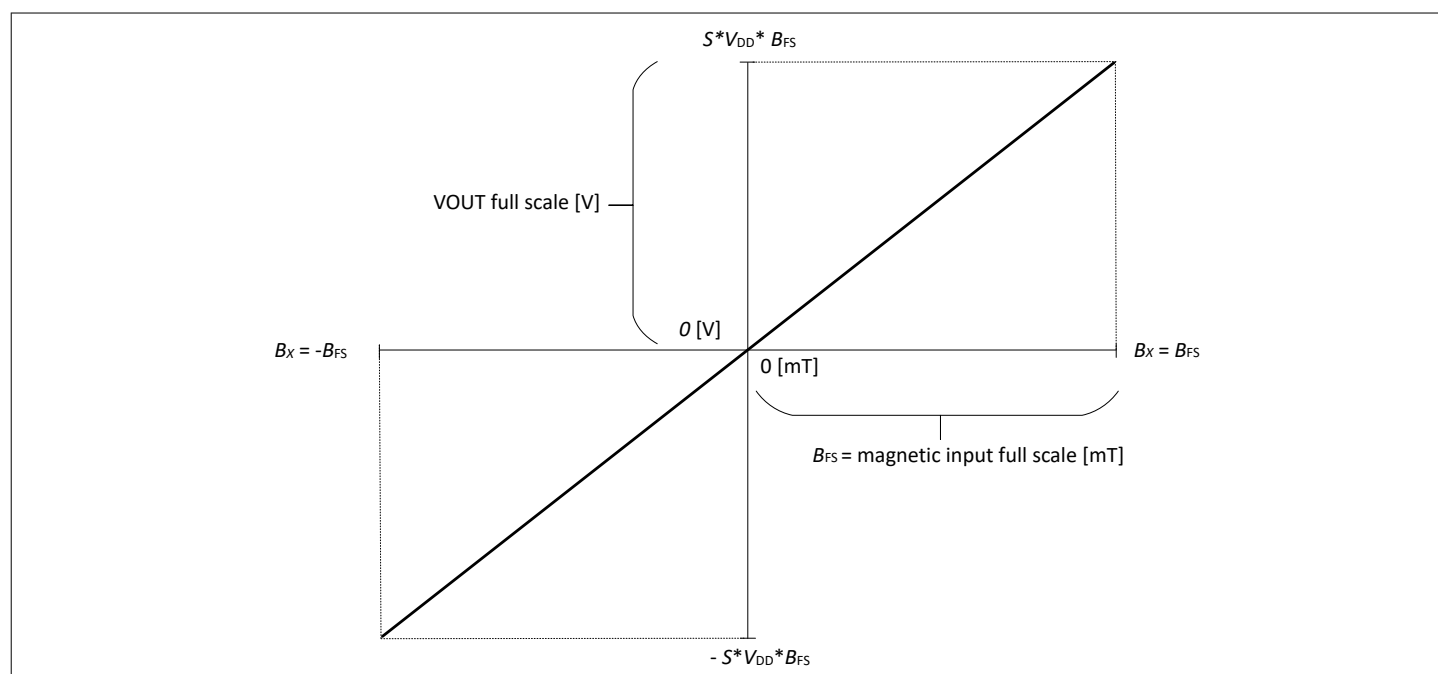
The sensor is sensitive to the sensing element plane magnetic field component directed from pin 5 to pin 2. The magnetic field on the sensing element location is positive when directed from pin 5 to pin 2. The sensor provides an output voltage  $V_{OUT}$  higher than 0V when the magnetic field is positive and lower than 0V when the magnetic field is negative.



**Figure 3** Polarity definition

### 4.3.2 Full scale definition

The magnetic input full scale and analog output full scale are defined in the following figure.



**Figure 4** Full scale ( $B_{FS}$ ) definition

The errors specified in [Chapter 4.2](#) are referred to the magnetic input full scale ( $B_{FS}$ ). Referring the errors to the whole  $[-B_{FS}... B_{FS}]$  range would reduce the errors by a factor of two.



### 4.3.3 Output behavior

The VP and VN pins operates as an output and provide an output voltage with high bandwidth. Being  $S$  the sensitivity and  $V_{OQ}$  the quiescent voltage of the sensor, the output voltage on VP and VN is described as follows:

$$V(VP) = V_{OQ} + \frac{S \cdot V_{DD}}{2} \cdot B_X = \frac{V_{DD}}{2} + \frac{S \cdot V_{DD}}{2} \cdot B_X \quad (1)$$

$$V(VN) = V_{OQ} - \frac{S \cdot V_{DD}}{2} \cdot B_X = \frac{V_{DD}}{2} - \frac{S \cdot V_{DD}}{2} \cdot B_X \quad (2)$$

Where  $B_X$  is the magnetic field at the TMR sensing element location for X sensitive direction. The differential output voltage  $VOUT$  is described as follows:

$$VOUT = V(VP) - V(VN) = S \cdot V_{DD} \cdot B_X \quad (3)$$

### 4.3.4 Output noise

Output noise referenced to magnetic input field can be expressed according to the following formula:

$$B_{NOISE} = \frac{V_{NOISE}}{S \cdot V_{DD}} \quad (4)$$

Where:

- $B_{NOISE}$  is the output noise referenced to magnetic input field [ $\mu T_{RMS}$ ]
- $V_{NOISE}$  is the output noise voltage in [ $\mu V_{RMS}$ ]
- $S$  is the sensitivity in [mV/V/mT]

### 4.3.5 Output error definitions and calculations

Initial offset ( $E_{OFF\_INIT}$ ) and initial sensitivity error ( $E_{SENS}$ ) are part-to-part variations that can be compensated by the customers at 0h and room temperature.

Both offset and sensitivity can drift due to temperature changes and lifetime effects. Temperature drifts are defined by the  $E_{OFF\_T}$ ,  $E_{SENS\_T}$  parameters.

If we consider sensitivity and offset drifts over temperature and over lifetime to have zero mean and statistically independent from each other, the total drift over temperature ( $E_{TOT\_T}$ ) expressed in % of the sensor full scale  $FS$  can be estimated as:

$$E_{OFF\_T} [\% FS] = \frac{|T_{CO\_max} - T_{CO\_min}|}{2} \cdot \frac{V_{DD} \cdot \Delta T}{FS[V]} \cdot 100 \% \quad (5)$$

$$E_{SENS\_T} [\% FS] = \frac{|T_{CS\_max} - T_{CS\_min}|}{2} \cdot \frac{[V(VP) - V(VN)] \cdot \Delta T}{FS[V]} \cdot 100 \% \quad (6)$$

$$E_{TOT\_T} [\% FS] = \sqrt{E_{OFF\_T} [\% FS]^2 + E_{SENS\_T} [\% FS]^2} \quad (7)$$

Additionally, the following error sources should be taken in consideration for the calculation of the total error at system level.

Output noise ( $B_{\text{NOISE}}$ ) is specified in  $[\mu\text{T}_{\text{RMS}}]$ , as explained in [Chapter 4.3.4](#). The RMS noise is dependent on utilized bandwidth in the application. The error due to the noise in % of full scale can be estimated as:

$$E_{\text{NOISE}} [\% \text{FS}] = \frac{B_{\text{NOISE}} [\mu\text{T}]}{FS_{[mT]} \cdot 10^3} \% \quad (8)$$

The residual offset and sensitivity errors after user calibration depend on the accuracy of the calibration environment. It is possible to consider them to have zero mean and being statistically independent from the other error components.

In case of variants with very low magnetic full scale range, and in case no shielding is done at system level, the Earth magnetic field contribution on the total error is non negligible and must be added arithmetically to the total error. The calculation below takes into account two times  $B_{\text{EARTH\_MAX}}$  because the  $B_{\text{EARTH}}$  seen by the sensor in the application can be oriented in the opposite direction with respect to the  $B_{\text{EARTH}}$  seen by the sensor during user calibration:

$$E_{\text{EARTH}} [\% \text{FS}] = \frac{2 \times B_{\text{EARTH\_MAX}} [mT]}{FS_{[mT]}} \% \quad (9)$$

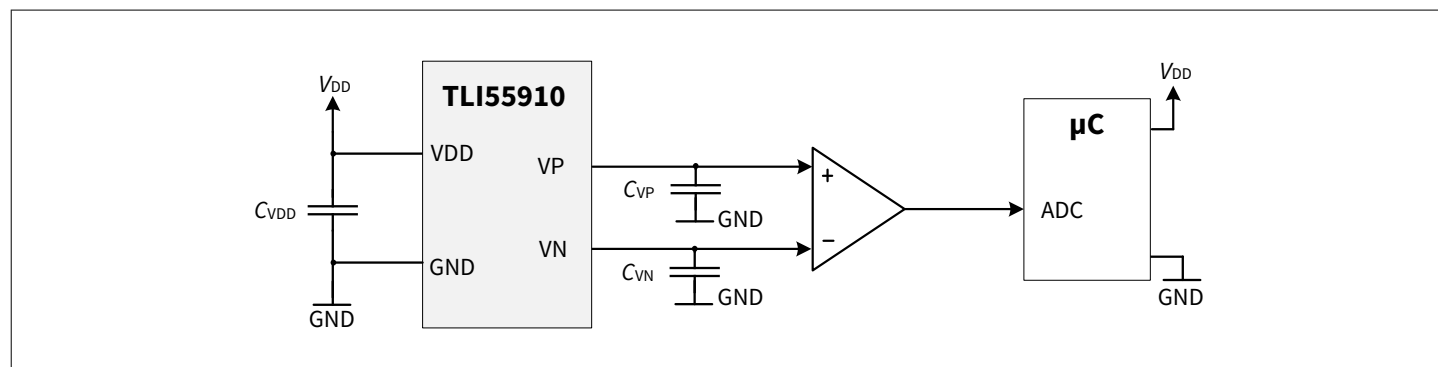
The total error from the sensor over temperature and lifetime can be estimated as:

$$E_{\text{TOT}} [\% \text{FS}] = E_{\text{EARTH}} + E_{\text{NL}} + \sqrt{E_{\text{HYST}}^2 + E_{\text{TOT\_T}}^2 + E_{\text{RES}}^2} \quad (10)$$

## 5 Application information

### 5.1 Application circuit

The figure below shows an example application circuit of the device. Please refer to [Table 3](#) for the value of passive components.



**Figure 5** Application circuit example

*Note: This is a simplified example of an application circuit. The function must be verified in the real application.*

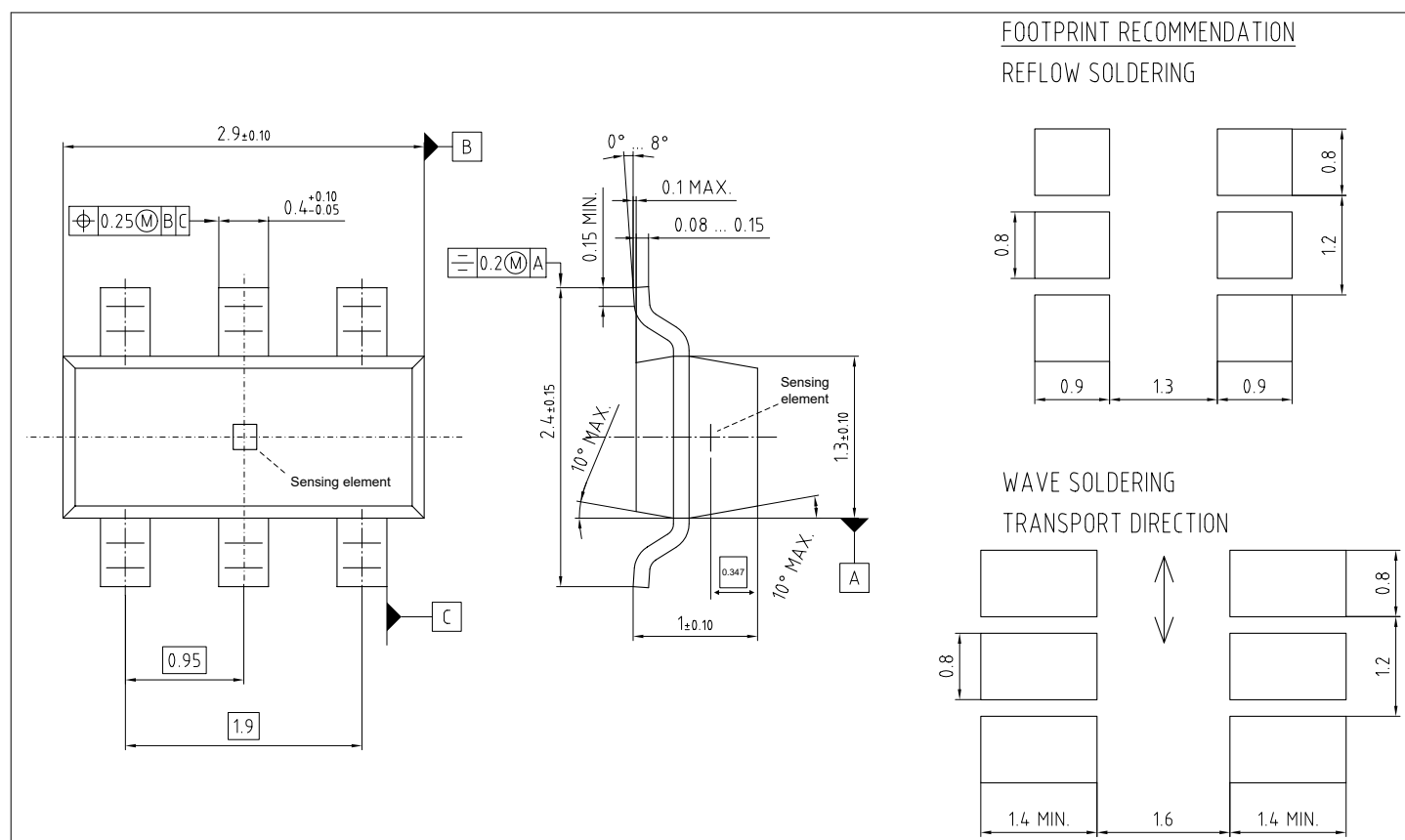
### 5.2 Initial offset error calibration procedure

The initial offset error  $V_{OFF}$  is defined as the output voltage  $V_{OUT}$  when no external magnetic field is applied:

$$V_{OFF} = V_{OUT_{0A}} = [V(VP) - V(VN)]_{0A} \quad (11)$$

## 6 Package

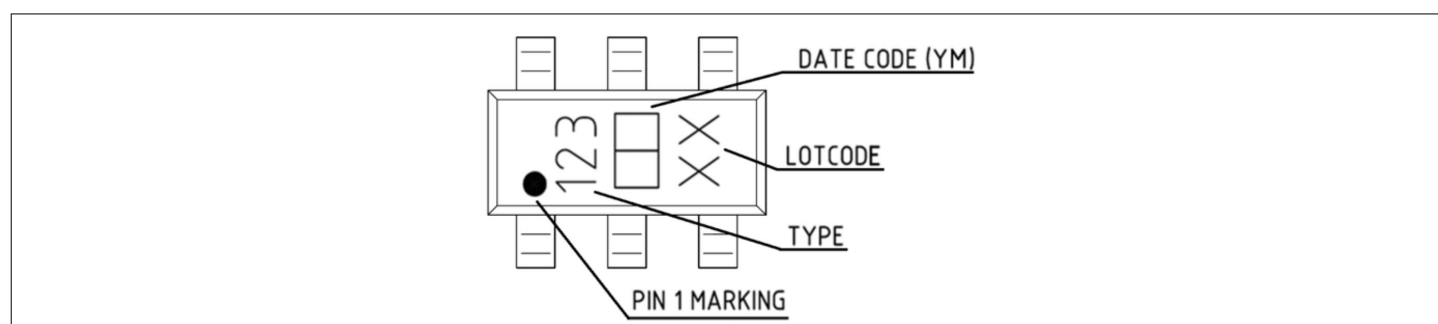
The device is mounted in the PG-SOT23-6-4 package.



**Figure 6 PG-SOT23-6-4 package outline. Sensing element dimensions and position are not in scale**

The PG-SOT23-6-4 package fulfills the MSL level 1 according to IPC/JEDEC J-STD-033C February 2012

The package marking of the device is as shown in the figure below.



**Figure 7 Package marking - front side**

7 Revision history

Table 7 Revision history

Revision number	Date of release	Description of changes
Rev. 1.00	2025-02-21	Initial release

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**Edition 2025-02-21**

**Published by**

**Infineon Technologies AG**  
**81726 Munich, Germany**

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**Document reference**  
**IFX-ecy1739784075434**

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